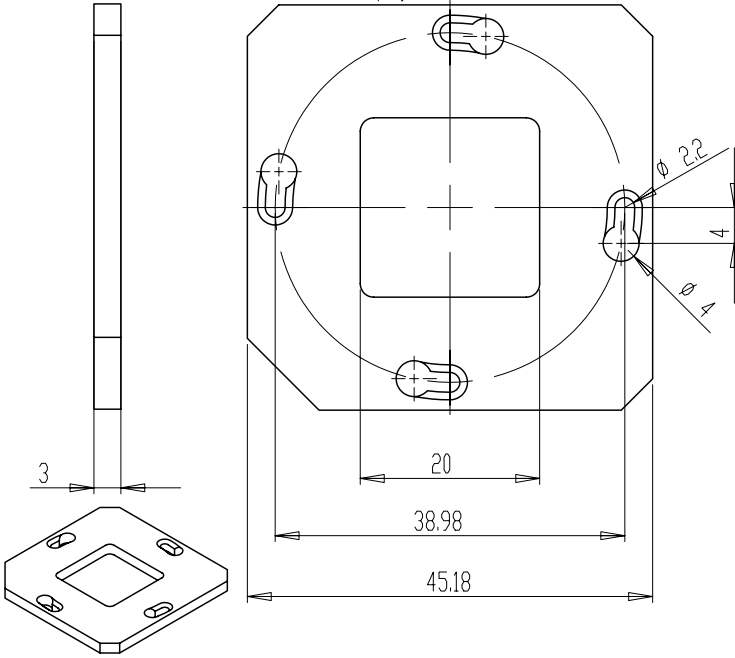


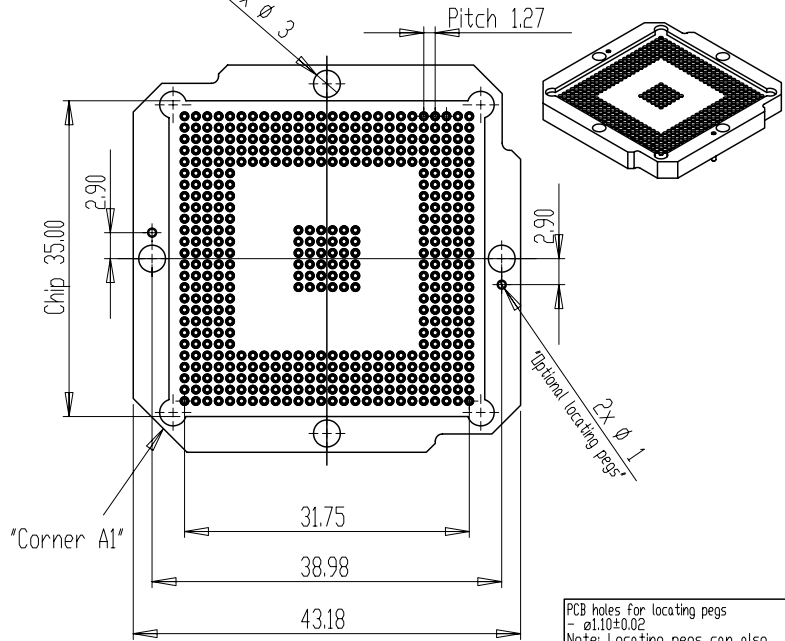
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	11/08/99	J.G.
B	UPDATED DRAWING & PAD LAYUOT	02/01/02	H.N.
C	UPDATED DRAWING W/ TWIST LOCK	04/20/07	H.N.

Retention frame  
Material: Epoxy FR4



Socket  
Material: TG 200  
Thickness: 4.50 mm

SKT954



PCB holes for locating pegs  
=  $\phi 1.10 \pm 0.02$   
Note: Locating pegs can also be soldered to PCB if plated-thru holes are provided

PACKAGE SPECIFICATIONS

PIN COUNT	= 456
LEAD PITCH	= 1.27mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 35.00mm SQ
IC BALL DIA	= 1.00mm MAX.
BALL HEIGHT	= 0.70mm MAX.

UNLESS OTHERWISE SPECIFIED:  
DIMENSIONS ARE IN MILLIMETERS  
SURFACE FINISH:  
GENERAL TOLERANCES:  $\pm 0.10$   
LINEAR:  
ANGULAR:

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED

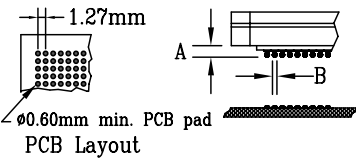
RECOMMENDED PAD LAYOUT

SURFACE MOUNT STYLE

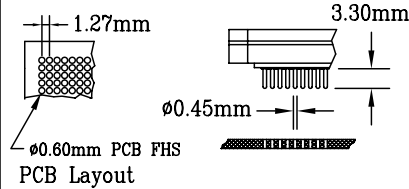
REGULAR SMT STYLE	RAISED SMT STYLE
XX = SM	XX = SR
YY = 30	YY = 29

SOLDERTAIL = THRU HOLE STYLE

XX = ET  
YY = 70



29= raised SMT: A = 5.00mm; B= 0.47mm  
30= standard SMT: A = 1.20mm; B= 0.47mm



PCB Layout

Emulation Technology, Inc.  
— VLSI and SMT ADAPTERS and ACCESSORIES —

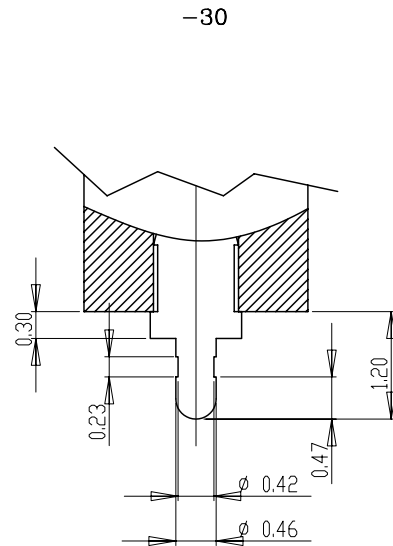
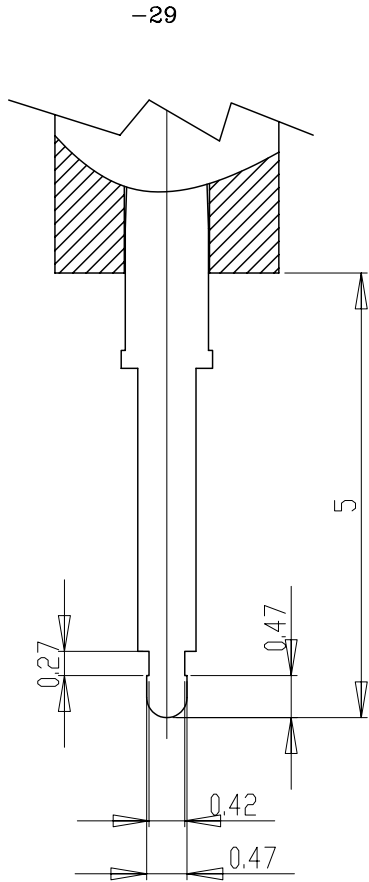
2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051  
TEL:(408)982-0660  
FAX:(408)982-0664


SHEET: 1 OF 1	DATE: 02/01/02	REVISION: C	<b>ASSEMBLY DRAWING</b>
CHECKED:	DRAWN: H.N.	ITEM: S-BGA-26-456-XX	
Scale N/A		DO NOT SCALE DRAWING	DESCRIPTION: BPW-456-2BG026-YY

All Dimensions Are Nominal For A 1.27mm Pitch BGA Package

REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	06/28/06	H.N.

ET-1.27mm



ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED			
		<b>Emulation Technology, Inc.</b> — VLSI and SMT ADAPTERS and ACCESSORIES —	
		2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051 TEL:(408)982-0660 FAX:(408)982-0664	
SHEET: 1 OF 1	DATE: 06/28/06	REVISION: A	<b>ASSEMBLY DRAWING</b>
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: 1.27mm PITCH PIN	DESCRIPTION: 1.27mm PITCH PIN
Scale N/A	DO NOT SCALE DRAWING		